Product Preview

64K x 18 Bit BurstRAM™ Synchronous Fast Static RAM

With Burst Counter and Self-Timed Write

The MCM69H618 is a 1,179,648 bit synchronous fast static random access memory designed to provide a burstable, high--performance, secondary cache for the i486™ and Pentium™ microprocessors. It is organized as 65,536 words of 18 bits, fabricated with Motorola's high--performance silicon-gate BiCMOS technology. The device integrates input registers, a 2-bit counter, high speed SRAM, and high drive capability outputs onto a single monolithic circuit for reduced parts count implementation of cache data RAM applications. Synchronous design allows precise cycle control with the use of an external clock (K). BiCMOS circuitry reduces the overall power consumption of the integrated functions for greater reliability.

Addresses (A0 – A15), data inputs (D0 – D17), and all control signals except output enable (\overline{G}) are clock (K) controlled through positive–edge–triggered noninverting registers.

Bursts can be initiated with either address status processor (ADSP) or address status cache controller (ADSC) input pins. Subsequent burst addresses can be generated internally by the MCM69H618 (burst sequence imitates that of the i486 and Pentium) and controlled by the burst address advance (ADV) input pin. The following pages provide more detailed information on burst controls.

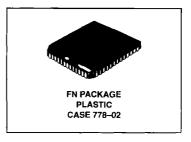
Write cycles are internally self-timed and are initiated by the rising edge of the clock (K) input. This feature eliminates complex off-chip write pulse generation and provides increased flexibility for incoming signals.

Dual write enables ($\overline{\text{LW}}$ and $\overline{\text{UW}}$) are provided to allow individually writeable bytes. $\overline{\text{LW}}$ controls DQ0 – DQ8 (the lower bits), while $\overline{\text{UW}}$ controls DQ9 – DQ17 (the upper bits)

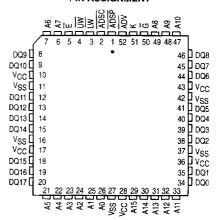
This device is ideally suited for systems that require wide data bus widths and cache memory. See Figure 2 for applications information.

- Single 3.3 V ± 5% Power Supply
- Fast Access Times: 8/10/12 ns Max
- · Byte Writeable via Dual Write Enables
- Internal Input Registers (Address, Data, Control)
- Internally Self–Timed Write Cycle
- ADSP, ADSC, and ADV Burst Control Pins
- Asynchronous Output Enable Controlled Three-State Outputs
- · Common Data Inputs and Data Outputs
- 5 V Tolerant I/O
- High Board Density 52-Lead PLCC Package
- ADSP Disabled with Chip Enable (E) Supports Address Pipelining

MCM69H618



PIN ASSIGNMENT



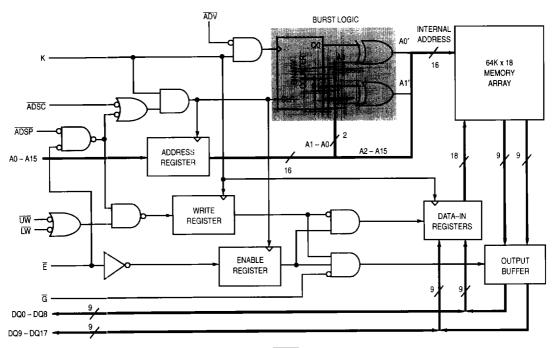
PIN NAMES
A0 - A15 Address Inputs
K Clock
ADV Burst Address Advance
LW Lower Byte Write Enable
UW Upper Byte Write Enable
ADSC Controller Address Status
ADSP Processor Address Status
Ē Chip Enable
G Output Enable
DQ0 - DQ17 Data Input/Output
Vcc + 3.3 V Power Supply

All power supply and ground pins must be connected for proper operation of the device.

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This document contains information on a product under development. Motorola reserves the right to change or discontinue this product without notice.

BLOCK DIAGRAM (See Note)



NOTE: All registers are positive–edge triggered. The ADSC or ADSP signals control the duration of the burst and the start of the next burst. When ADSP and E are sampled low, any ongoing burst is interrupted and a read (independent of W and ADSC) is performed using the new external address. Alternatively, an ADSP-initiated two cycle WRITE can be performed by asserting ADSP, E, and a valid address on the first cycle, then negating both ADSP and ADSC and asserting LW and/or UW with valid data on the second cycle (see Single Write Cycle in WRITE CYCLES timing diagram). Note that when E and ADSC are high, ADSP is ignored – the external address is not registered in this case.

When $\overline{\mathsf{ADSC}}$ is sampled low (and $\overline{\mathsf{ADSP}}$ is sampled high), any ongoing burst is interrupted and a read or write (dependent on $\overline{\mathsf{W}}$) is performed using the new external address. Chip enable ($\overline{\mathsf{E}}$) is sampled only when a new base address is loaded. After the first cycle of the burst, $\overline{\mathsf{ADV}}$ controls subsequent burst cycles. When $\overline{\mathsf{ADV}}$ is sampled low, the internal address is advanced prior to the operation. When $\overline{\mathsf{ADV}}$ is sampled high, the internal address is not advanced, thus inserting a wait state into the burst sequence accesses. Upon completion of a burst, the address will wrap around to its initial state. See **BURST SEQUENCE TABLE**. Write refers to either or both byte write enables ($\overline{\mathsf{LW}}$, $\overline{\mathsf{UW}}$).

BURST SEQUENCE TABLE (See Note)

External Address	A15 – A2	A1	A0
1st Burst Address	A15 – A2	A1	ĀŪ
2nd Burst Address	A15 – A2	Ā1	A0
3rd Burst Address	A15 A2	Ā1	Ā0

NOTE: The burst wraps around to its initial state upon completion.

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SYNCHRONOUS TRUTH TABLE (See Notes 1, 2, and 3)

Ê	ADSP	ADSC	ADV	UW or LW	К	Address Used	Operation
Н	Х	L	Х	Х	L-H	N/A	Deselected
L	L	X	Х	Х	L–H	External Address	Read Cycle, Begin Burst
L	H	L	X	L	L-H	External Address	Write Cycle, Begin Burst
L	Н	L	Х	Н	L-H	External Address	Read Cycle, Begin Burst
X	Н	Н	L	L	L-H	Next Address	Write Cycle, Continue Burst
X	H	н	L	Н	L-H	Next Address	Read Cycle, Continue Burst
X	Н	Н	н	L	L-H	Current Address	Write Cycle, Suspend Burst
Х	Н	н	Н	Н	L-H	Current Address	Read Cycle, Suspend Burst
Н	х	Н	L	L	L-H	Next Address	Write Cycle, Continue Burst
Н	X	н	L	Н	L-H	Next Address	Read Cycle, Continue Burst
Н	х	Н	Н	L	L-H	Current Address	Write Cycle, Suspend Burst
Н	Х	н	Н	Н	L-H	Current Address	Read Cycle, Suspend Burst

NOTES:

- 1. X means Don't Care.
- 2. All inputs except \overline{G} must meet setup and hold times for the low-to-high transition of clock (K).
- 3. Wait states are inserted by suspending burst.

ASYNCHRONOUS TRUTH TABLE (See Notes 1 and 2)

	,	•
Operation	Ğ	I/O Status
Read	L	Data Out
Read	н	High-Z
Write	Х	High-Z Data In
Deselected	X	HighZ

NOTES:

- 1. X means Don't Care.
- 2. For a write operation following a read operation. \$\bar{G}\$ must be high before the input data required setup time and held high through the input data hold time.

ABSOLUTE MAXIMUM RATINGS (Voltages Referenced to $V_{SS} = 0 \text{ V}$)

Rating	Symbol	Value	Unit		
Power Supply Voltage	V _C C	- 0.5 to + 7.0	V		
Voltage Relative to VSS for Any Pin Except VCC	Vin. Vout	- 0.5 to V _{CC} + 0.5	٧		
Output Current (per I/O)	l _{cut}	± 30	mA		
Power Dissipation	Po	1.5	W		
Temperature Under Bias	T _{bias}	- 10 to + 85	°C		
Operating Temperature	TA	0 to +70	°C		
Storage Temperature	T _{stg}	- 55 to + 125	°C		

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPER-ATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

This BiCMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established.

This device contains circuitry that will ensure the output devices are in High-Z at power up.

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DC OPERATING CONDITIONS AND CHARACTERISTICS

 $(V_{CC} = 3.3 \text{ V} \pm 5\%, T_A = 0 \text{ to} + 70^{\circ}\text{C}, \text{ Unless Otherwise Noted})$

RECOMMENDED OPERATING CONDITIONS (Voltages referenced to VSS = 0 V)

Parameter	Symbol	Min	Max	Unit
Supply Voltage (Operating Voltage Range)	Vcc	3.135	3.465	٧
Input High Voltage	VIH	2.2	5.5**	٧
Input Low Voltage	VIL	- 0.5*	0.8	٧

^{*} $V_{IL} \ge -2 \text{ V for } t \le t_{KHKH}/2$.
** $V_{IH} \le 6 \text{ V for } t \le t_{KHKH}/2$.

DC CHARACTERISTICS AND SUPPLY CURRENTS

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, V _{in} = 0 to V _{CC})	llkg(l)	_	± 1.0	μА
Output Leakage Current (G = V _{IH})	likg(O)		± 1.0	μА
AC Supply Current (\overline{G} = V _{IH} , \overline{E} = V _{IL} , I _{Out} = 0 mA, All Inputs = V _{IL} or V _{IH} , V _{IL} = 0.0 V and V _{IH} \geq 3.0 V, Cycle Time \geq t _{KHKH} min)	ICCA8 ICCA10 ICCA12		290 265 250	mA
AC Standby Current (\overline{E} = V _{IH} , I _{out} = 0 mA, All Inputs = V _{IL} and V _{IH} , V _{IL} = 0.0 V and V _{IH} \geq 3.0 V, Cycle Time \geq t _{KHKH} min)	ISB1	_	TBD	mA
Output Low Voltage (IOL = + 8.0 mA)	VOL		0.4	V
Output High Voltage (IOH = - 4.0 mA)	Voн	2.4	_	V

NOTE: Good decoupling of the local power supply should always be used. DC characteristics are guaranteed for all possible i486 and Pentium bus cycles.

CAPACITANCE (f = 1.0 MHz, dV = 3.0 V, T_A = 25°C, Periodically Sampled Rather Than 100% Tested)

Parameter	Symbol	Тур	Max	Unit
Input Capacitance (All Pins Except DQ0 – DQ17)	C _{in}	3	5	pF
Input/Output Capacitance (DQ0 – DQ17)	C _{I/O}	6	8	рF

AC OPERATING CONDITIONS AND CHARACTERISTICS

(V_{CC} = 3.3 V \pm 5%, T_A = 0 to + 70°C, Unless Otherwise Noted)

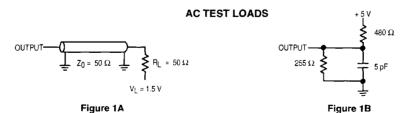
Input Timing Measurement Reference Level 1.5 V	Output Timing Reference Level
Input Pulse Levels 0 to 3.0 V	Output Load See Figure 1A Unless Otherwise Noted
Input Rise/Fall Time 2 ns	

READ/WRITE CYCLE TIMING (See Notes 1, 2, 3, and 4)

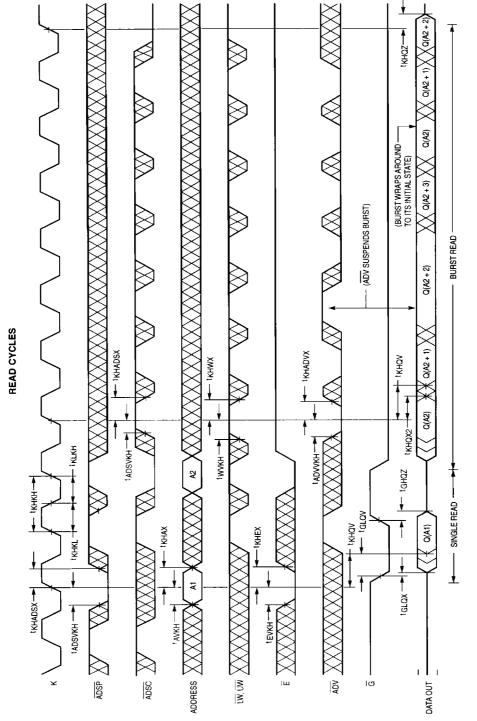
		мсм69Н618-8		MCM69H618-10		MCM69H618-12			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Cycle Time	tkhkh	15	_	16.6	-	20	_	ns	
Clock Access Time	tkhQV		8	-	10	-	12	ns	5
Output Enable to Output Valid	†GLQV	-	5	_	5	-	6	ns	
Clock High to Output Active	^t KHQX1	5		5		5		ns	
Clock High to Output Change	tkHQX2	2		2	_	2		ns	
Output Enable to Output Active	^t GLQX	0		0		0		ns	
Output Disable to Q High-Z	tGHQZ	2	5	2	5	2	6	ns	6
Clock High to Q High-Z	tkHQZ		5	_	5	_	6	ns	
Clock High Pulse Width	^t KHKL	4.5	_	5		6	-	ns	
Clock Low Pulse Width	tKLKH	4.5		5		6		ns	
Setup Times: Address Address Status Data In Write Address Advance Chip Enable	tavkh tadsvkh tovkh twvkh tadvvkh tevkh	25	_	2.5	_	2.5		ns	7
Hold Times: Address Address Status Data In Write Address Advance Chip Enable	tKHAX tKHADSX tKHDX tKHWX tKHADVX tKHADVX	05		0.5	_	0.5		ns	7

NOTES:

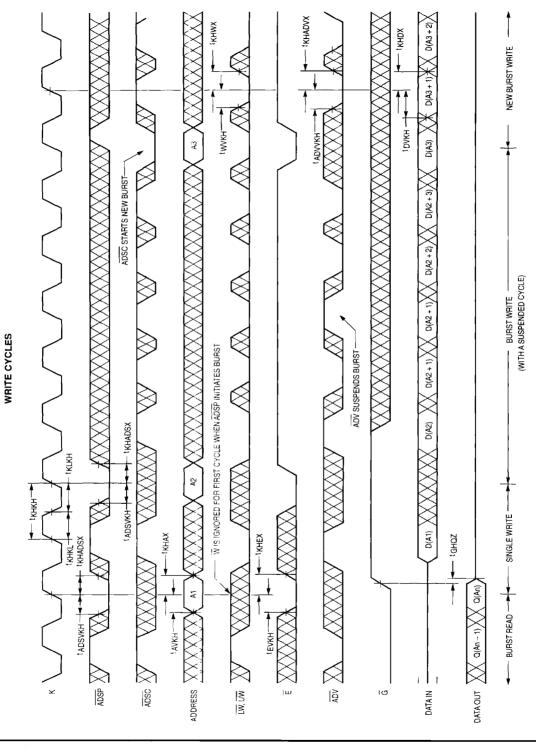
- 1. In setup and hold times, W (write) refers to either one or both byte write enables LW and UW.
- 2. A read cycle is defined by $\overline{\mathsf{LW}}$ and $\overline{\mathsf{LW}}$ high or $\overline{\mathsf{ADSP}}$ low for the setup and hold times. A write cycle is defined by $\overline{\mathsf{LW}}$ or $\overline{\mathsf{LW}}$ low and $\overline{\mathsf{ADSP}}$ high for the setup and hold times.
- 3. All read and write cycle timings are referenced from K or G.
- 4. G is a don't care when UW or LW is sampled low.
- 5. Maximum access times are guaranteed for all possible i486 and Pentium external bus cycles.
- 6. Transition is measured ± 500 mV from steady-state voltage with load of Figure 1B. This parameter is sampled rather than 100% tested. At any given voltage and temperature, IKHOZ max is less than IKHOZ1 min for a given device and from device to device.
- 7. This is a synchronous device. All addresses must meet the specified setup and hold times for ALL rising edges of K whenever ADSP or ADSC is low, and the chip is selected. All other synchronous inputs must meet the specified setup and hold times for ALL rising edges of K when the chip is enabled. Chip enable must be asserted at each rising edge of clock for the device (when ADSC is low) to remain enabled.



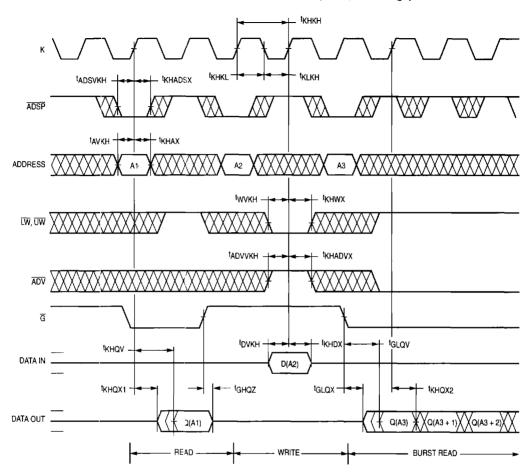
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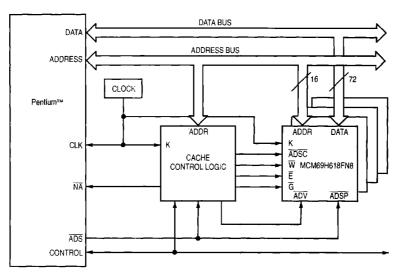
NOTE: Q(A2) represents the first output data from the base address A2; Q(A2 + 1) represents the next output data in the burst sequence with A2 as the base address.



COMBINATION READ/WRITE CYCLE (E low, ADSC high)

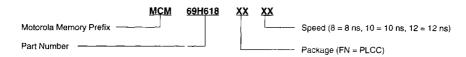


APPLICATION EXAMPLE



512K Byte Burstable, Secondary Cache Using Four MCM69H618FN8s with a 66 MHz (bus speed) Pentium

ORDERING INFORMATION (Order by Full Part Number)



Full Part Numbers — MCM69H618FN8 MCM69H618FN10 MCM69H618FN12

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